



Stock Code : 3114

Howtech Technology Co., Ltd.

2022 Investor Conference

2022/12/12

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Agenda

- Company Profile
- Financial Highlights
- Q & A

Company Profile

Stock Code	Date of Establishment	OTC Listing Date	Paid-in capital	Head Office
3114	1978/9/23	2004/3/25	NTD 626,248,000	Taipei City, Taiwan
Main Business	Electronic components and equipment import and export agency and trading business ° A. <u>Electronic Components</u> Agent sales of connectors, wires, electro-acoustic products and semiconductor components. B. <u>Equipment</u> Printed circuit board/flexible board process equipment (dry or wet process, horizontal process, punching machine, steel plate cleaning machine, plate receiving machine, stamping machine, etc.), process-related chemicals and consumables agent distribution.			

Business Philosophy

Conduct and Develop Business with Good Virtue

For over four decades of business operation in the fields of electronic information technology, HOWTEH always adheres to the core values of 『Trust and Community』, 『Improvement of Quality』, 『Best Service to Customers』 and 『Innovation and Growth』, and is committed to providing the service with the highest quality to customers of high-tech industry.

Trust and
Community

Improvement
of Quality

Best Service
to Customers

Innovation
and
Growth



Vision & Mission

Vision



Become a good partner
of colleagues,
customers,
shareholders, and
principals to create the
future together.

Become a first-class
supplier of high-value
accessory solutions in
the 3C field

Mission

Business Office

Howteh Group is headquartered in Taipei City, with 6 business offices in China and Vietnam.

集團總部-台北
Group Head Office-Taipei

中國
China

越南
Vietnam

華北
(North China)
北京(Beijing)

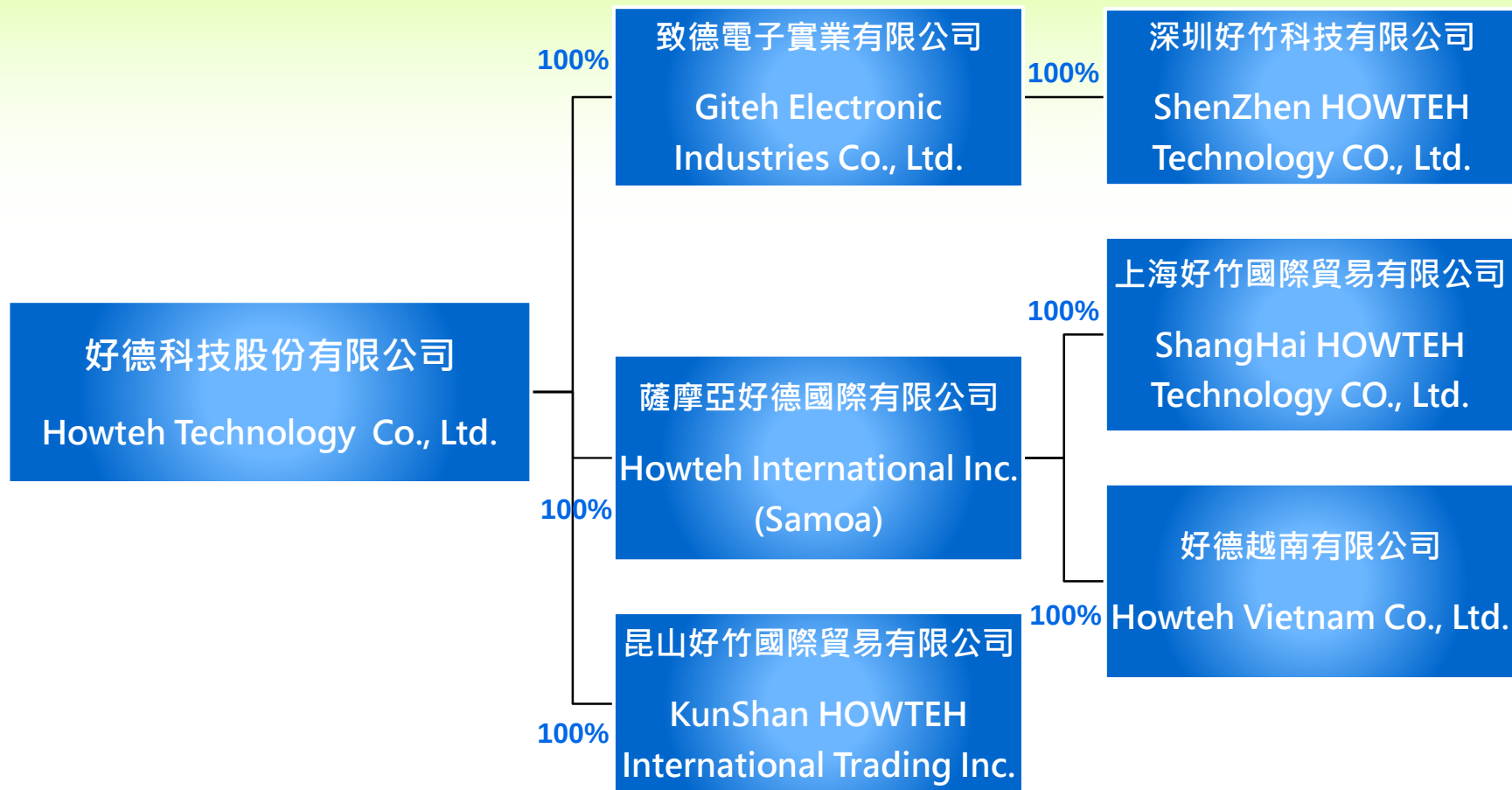
華東
(East China)
上海(Shanghai)
昆山(Kunshan)

華南
(South China)
深圳(Shenzhen)

香港
(Hong Kong)

河內
(Hanoi)

Company Investment Structure



Key Principals

Parts :

Principal	Product	Application field
Japan Aviation Electronics Industry, Ltd. (Japan) 	➤ Connectors • Board to Board/Cable/FPC • Memory Card/Type-C • Input / Output (I/O) • Automotive electronics • EV Charger	Computers, Communications, Mobile Phones, Electric Vehicles, New Energy Vehicles, Internet of Things, Internet of Vehicles, Metaverse, Industrial Equipment and Other Industries
Sumitomo Electric Industries, Ltd. (Japan) 	➤ Flexible Flat Cable(FFC)/FPC ➤ Thunderbolt Cable ➤ USB Cable ➤ High Speed Cable ➤ Coaxial Cable	High Speed Transmission -NB and Server -Storage device

Key Principals

Parts :

Principal	Product	Application field
Knowles Electronics · LLC (USA) 	➤ MEMS Microphone ➤ Balance Armature Receiver ➤ Hearing Health Components ➤ AlSonic	Components used in NB and camera modules, mid-to-high-end mobile phones, earphones, voice equipment, hearing aids, smart speakers, wearables and other products
Awinic Technology Co., Ltd. (China) 	➤ Audio IC ➤ Touch & Haptic IC ➤ LED Driver IC ➤ Battery Charge IC ➤ RF Components	Mobile Phones, Artificial intelligence, Internet of Things, Automotive Electronics, Wearable and Consumer Electronics and Many Other Fields

Main Principals

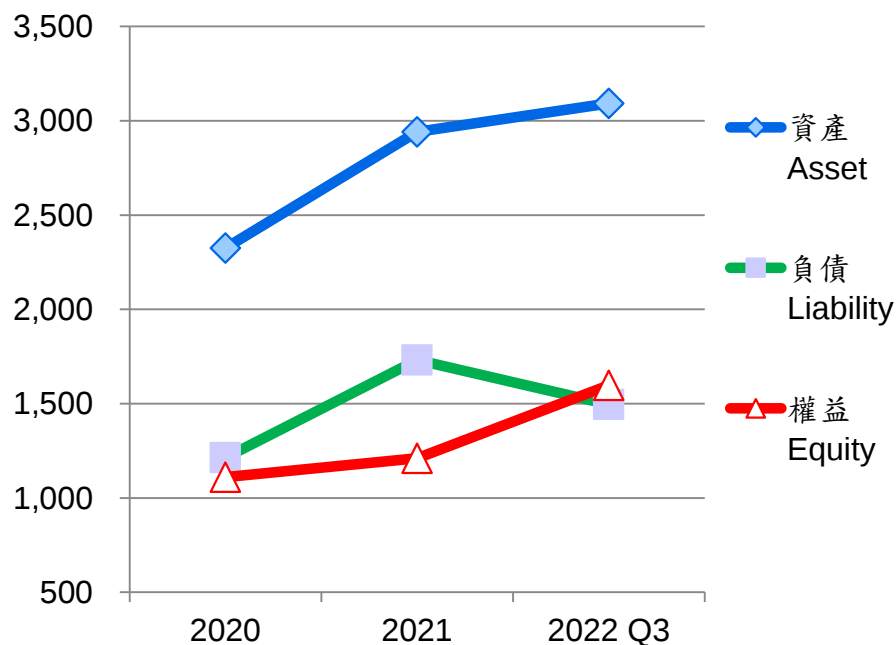
Equipment :

- **Self-designed PCB Wet Process Horizontal Equipment**
 - DES Line/RTR Line Development Line/RTR Stripping Line/SBS LPSM Pre-Micro-Etching Treatment Line
- **Canon Machinery Inc. (Japan)**
(Electronic Components-related Products)
 - New Hot Press Machine
 - Singulation Machine
- **API Corporation (Japan)**
(Spray Coater System for Nanotech)
- **Noritake co. limited (Japan)**
(Grinding and Polishing Tools)
 - Diamond Tools
 - Cutting Knife

The Latest Balance Sheet

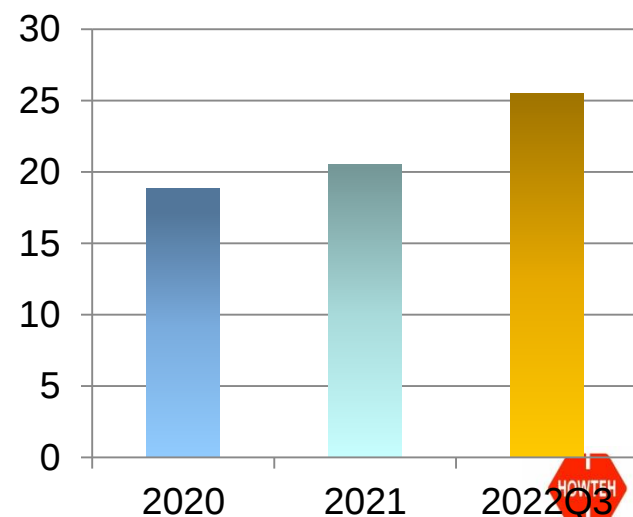
Unit: NTD1,000,000

Period		2022Q3	2021Q3	2021	2020
Condensed Balance Sheet	Total Assets	3,092	2,482	2,942	2,325
	Total Liabilities	1,495	1,346	1,731	1,214
	Total Equity	1,597	1,136	1,211	1,111
	Net Value Per Share	25.50	19.23	20.50	18.80

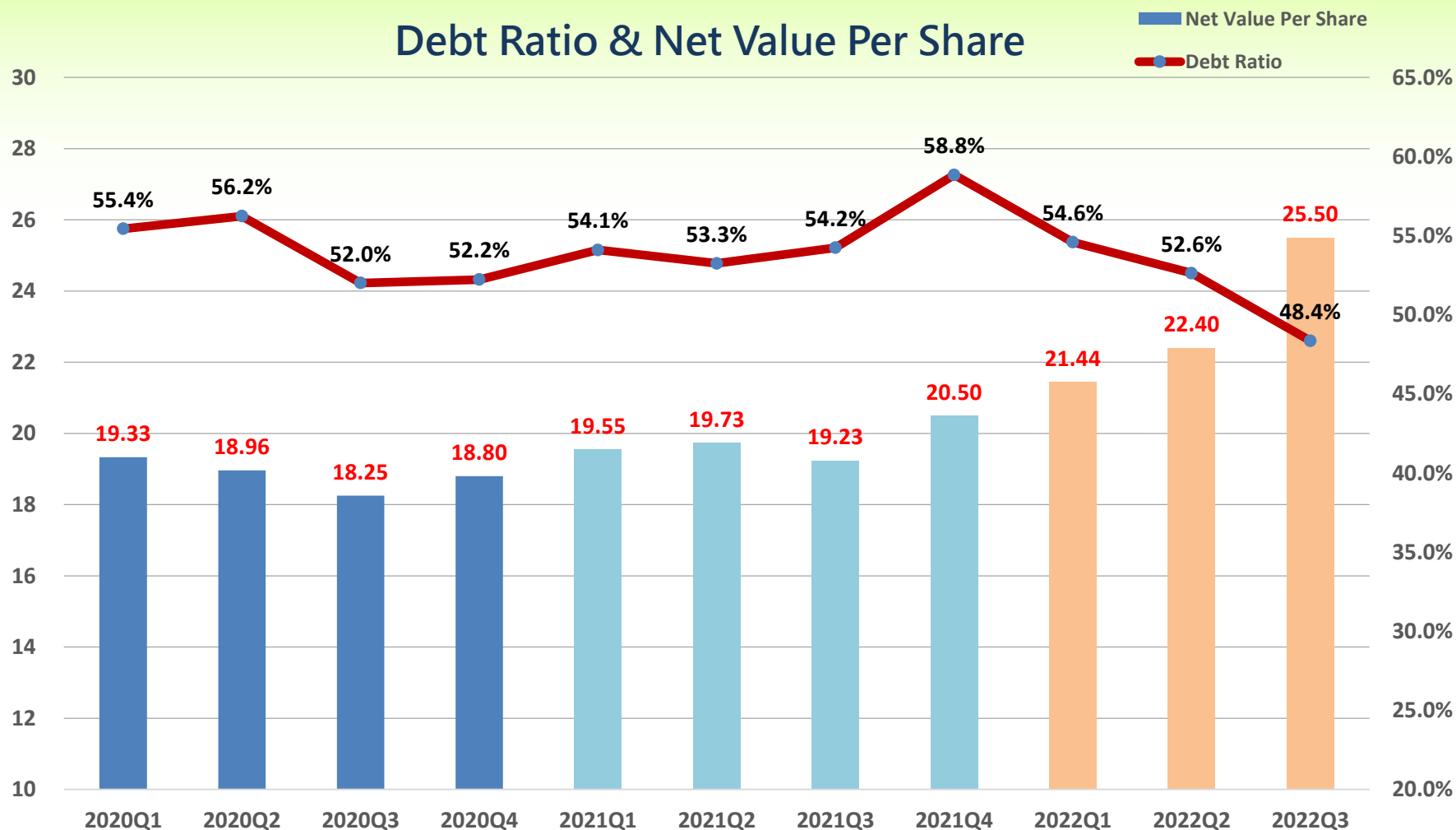


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Net Value Share



Debt Ratio & Net Value Per Share

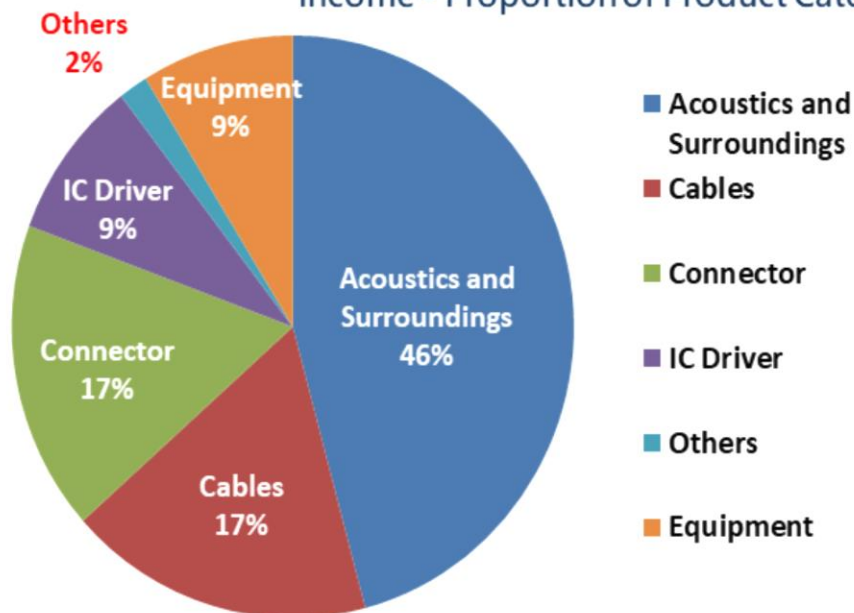


The Latest Income Statement

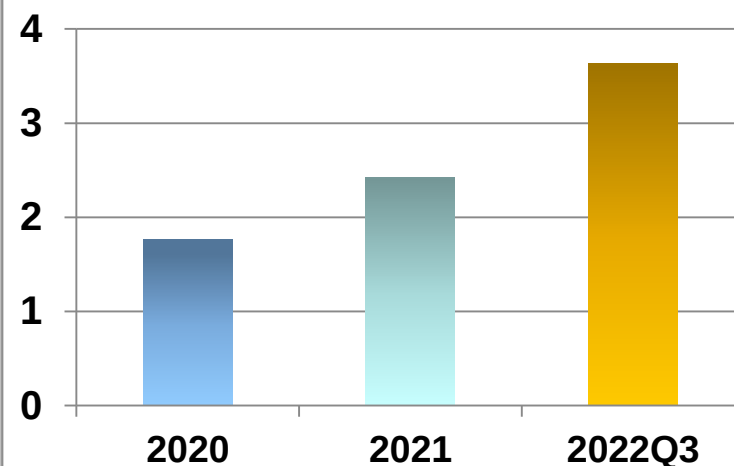
Unit : NTD 1,000,000

Period		2022 Q3	2021 Q3	2021	2020
Comprehensive Income Statement	Sales Revenue	2,527	2,682	3,721	3,188
	Profit From Operation	125	132	170	132
	Net Profit Before Tax	280	134	173	126
	Basic E.P.S. (Per \$)	3.63	1.89	2.42	1.76

Income - Proportion of Product Category



EPS (Unit: NTD)

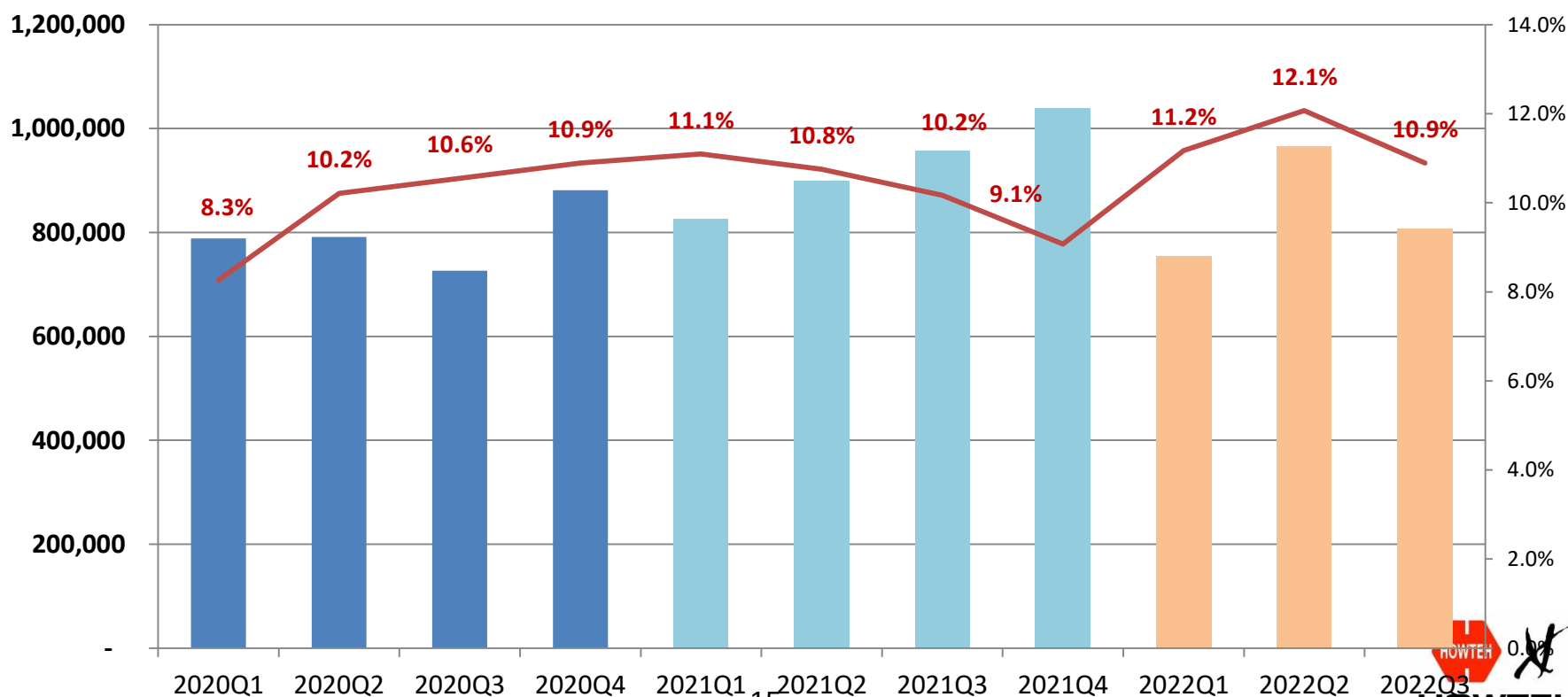


Latest 3 Years Sales & Margin Ratio

Unit: NTD 1,000

年度/季度	2020Q1	2020Q2	2020Q3	2020Q4	2021Q1	2021Q2	2021Q3	2021Q4	2022Q1	2022Q2	2022Q3
Sales	788,786	791,494	726,355	881,323	825,378	898,814	957,589	1,039,352	754,585	964,794	807,947
Margin %	8.3%	10.2%	10.6%	10.9%	11.1%	10.8%	10.2%	9.1%	11.2%	12.1%	10.9%

Latest 3 Years Sales vs Margin %

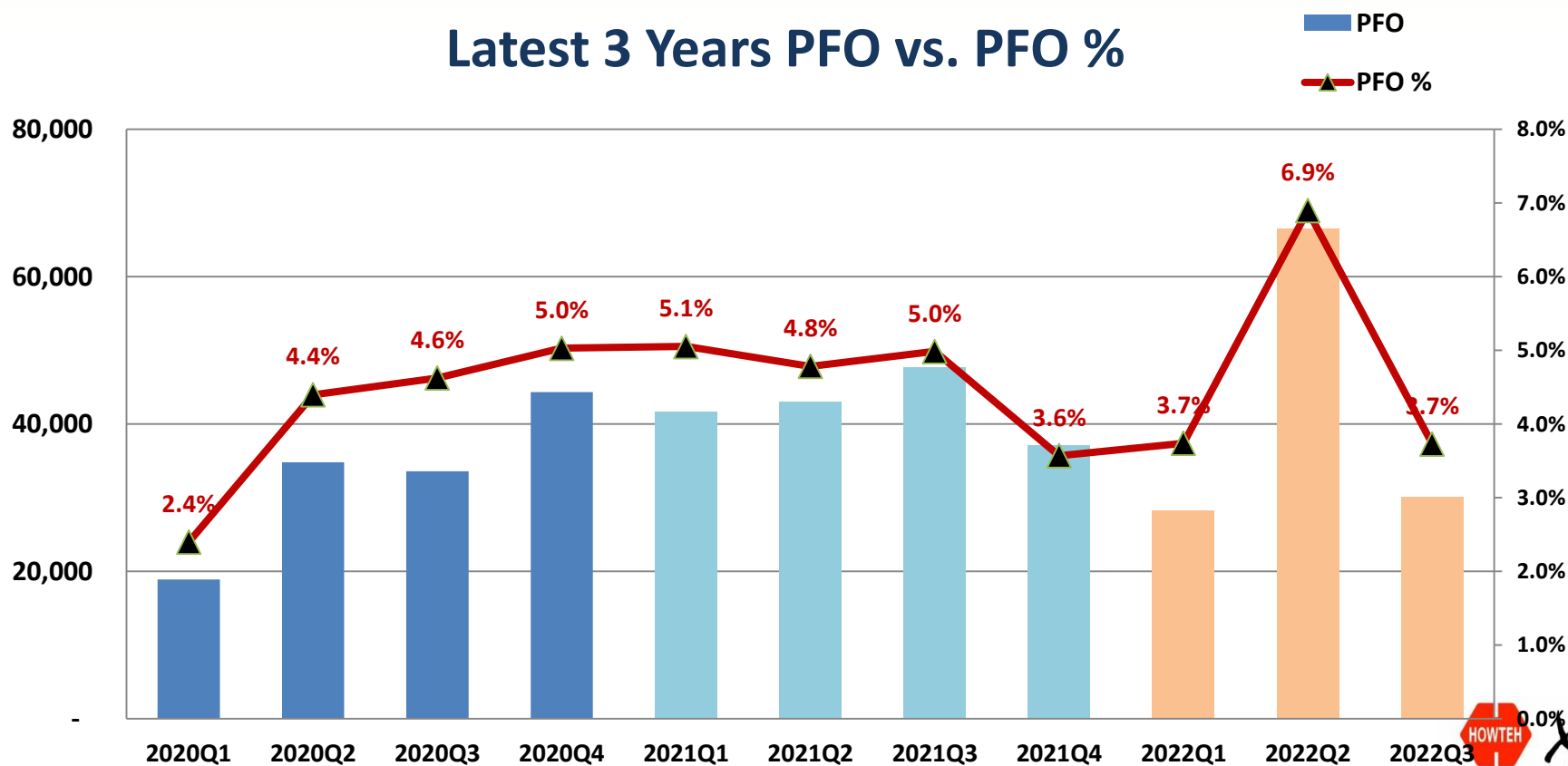


Latest 3 Years PFO vs. PFO Ratio

Unit: NTD 1,000

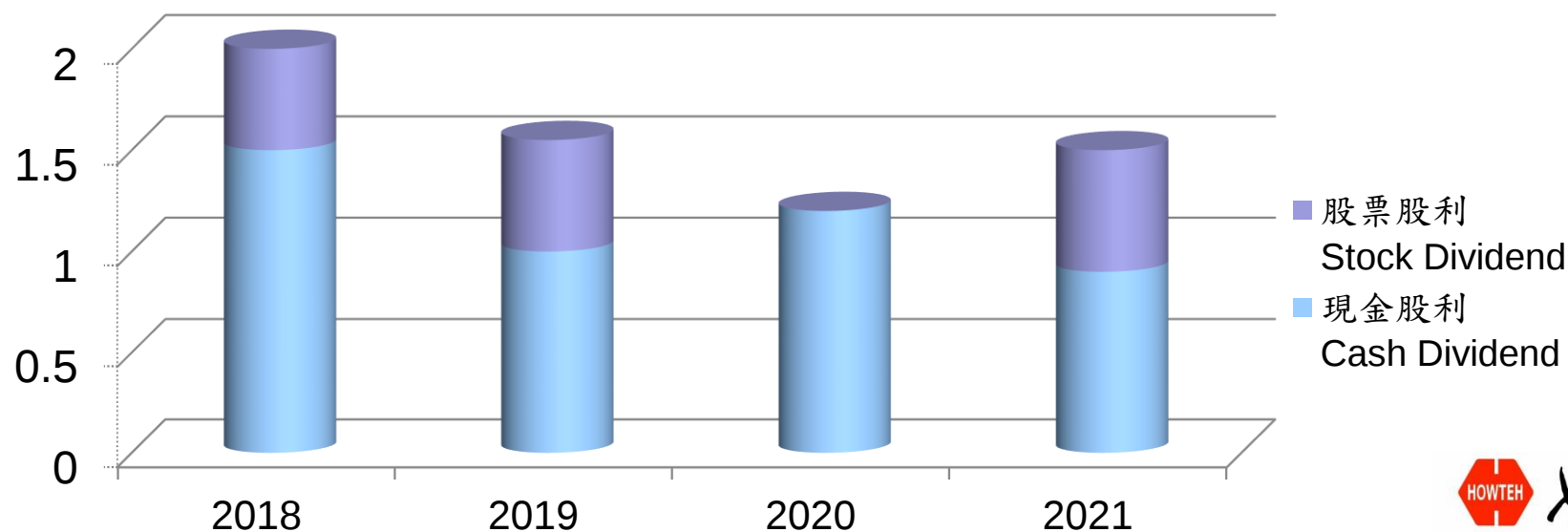
年度/季度	2020Q1	2020Q2	2020Q3	2020Q4	2021Q1	2021Q2	2021Q3	2021Q4	2022Q1	2022Q2	2022Q3
PFO	18,902	34,811	33,602	44,326	41,712	43,000	47,746	37,115	28,215	66,552	30,133
PFO %	2.4%	4.4%	4.6%	5.0%	5.1%	4.8%	5.0%	3.6%	3.7%	6.9%	3.7%

Latest 3 Years PFO vs. PFO %



Dividend Distribution in Recent Years

Year	2018	2019	2020	2021
EPS for The Year	3.16	2.54	1.76	2.42
Allotment Method				
Cash Dividend	1.50	1.00	1.20	0.90
Stock Dividend	0.766282	0.55		0.60
Allotment Amount	2.27	1.55	1.20	1.50



Q & A

Q & A

Thank You!